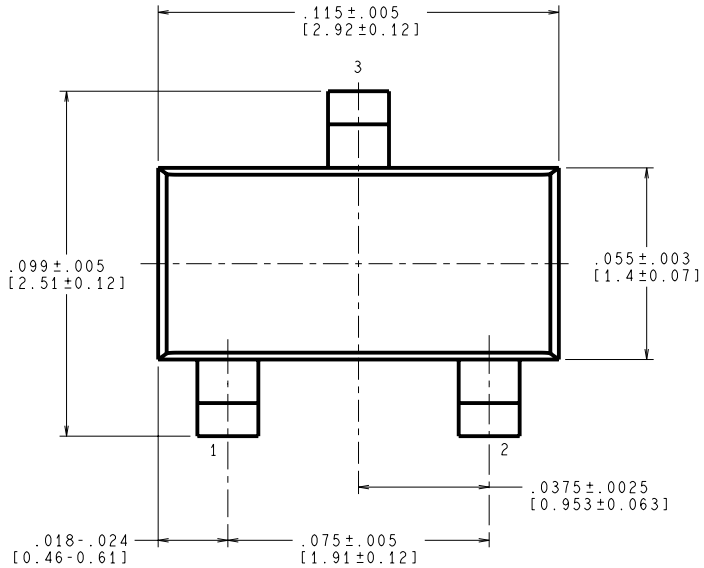
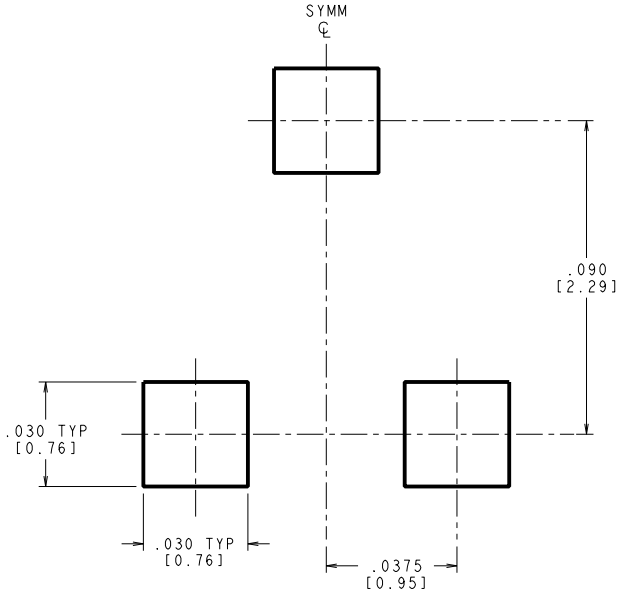
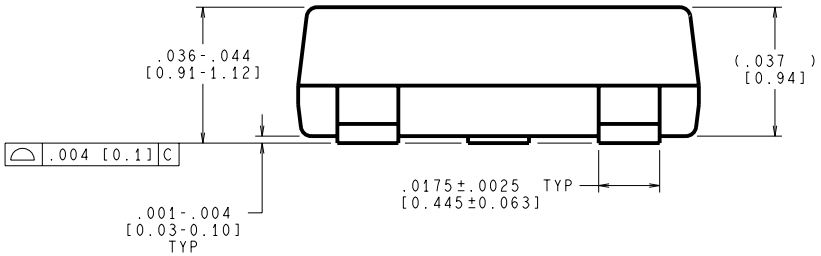
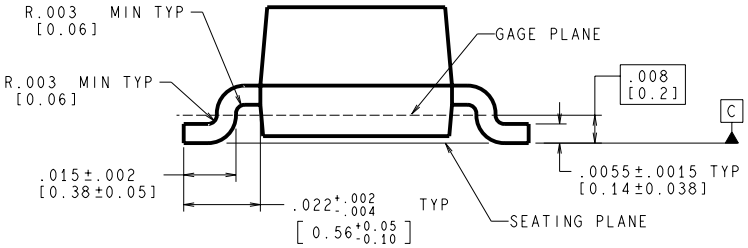
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11175	12/21/95	TL/OM
B	COPLANARITY .004[0.1] WAS .0015[0.038]; NOTE 1: 200 WAS 150, 5.08 WAS 3.81	11927	03/10/1998	MS/





LAND PATTERN RECOMMENDATION





CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH TO BE 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM TIN/LEAD (SOLDER) ON COPPER.
2. NO JEDEC REGISTRATION AS OF MAR 1998.

APPROVALS	DATE
DRAWN T. LEQUANG	12/21/95
DFTG. CHK.	
ENGR. CHK.	

PROJECTION INCH [MM]

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

MOLDED PACKAGE, SUPER-SOT, 3 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	(SC)MKT-MA03B	B

DO NOT SCALE DRAWING | SHEET 1 of 1